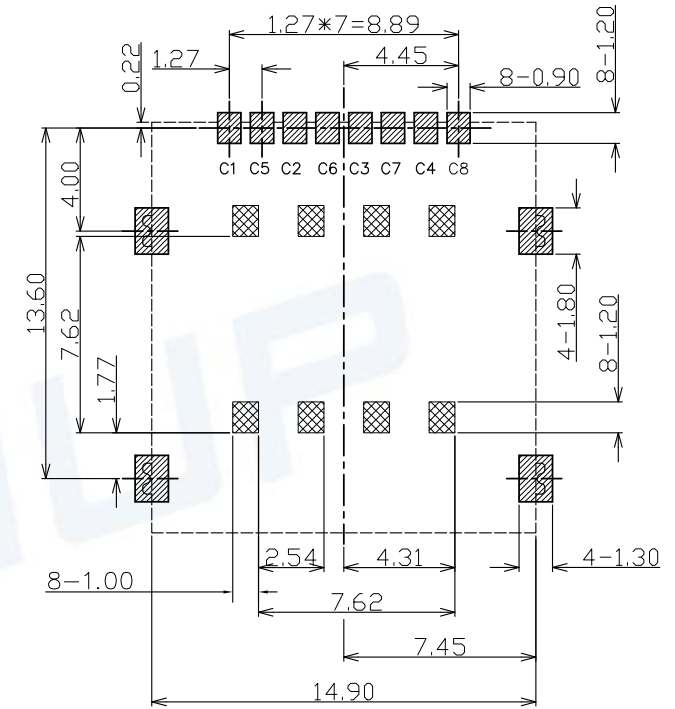
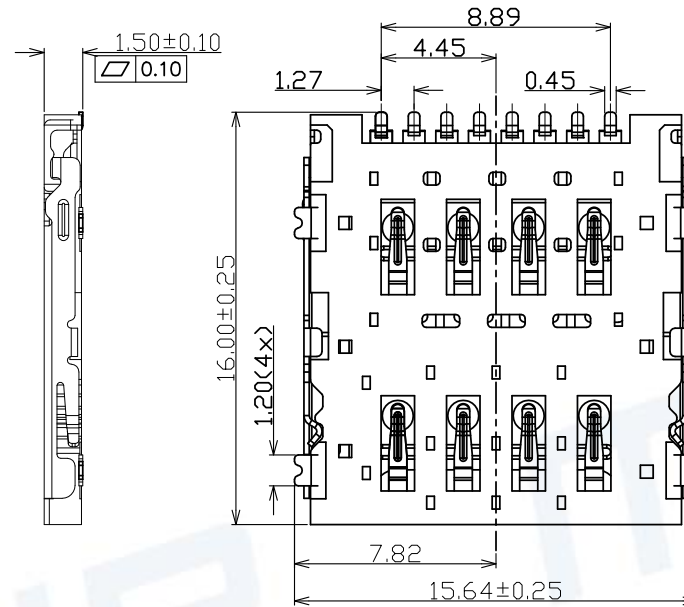
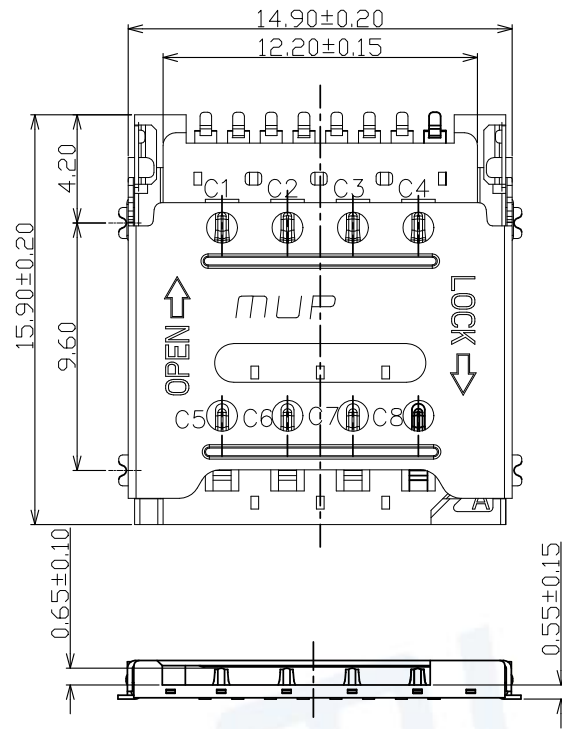


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Nov.29.2021
X2					



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)

**TECHNICAL CHARACTERISTICS**

- General Characteristics  
Dimensions:15.90LX14.90WX1.50H mm  
Weight:Approx 0.53±0.2g  
Durability:5,000 cycles min.
- Electrical Characteristics  
Contact resistance:50mΩ typical,  
100mΩMax  
Insulation resistance:>1000M/500V DC
- Solderability  
Vaporphase:215°C, 30sec.Max  
IR reflow:250°C,5sec.Max  
Manual soldering:370°C.3sec.Max
- Environmental Characteristics  
Operating temperature:-40°C~+85°C  
Operating humidity:10%~+95%RH

\*5.Note:  
It's easy to cause short-circuit between the shell and the fillet weld leg at the power is on when lift the cover greater than 135 degree .  
Suggestion:  
Do not lift the cover when the current is switched on.

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

- PAD AREA
- CONNECTOR OUTLINE
- NO PATTERN AND VIA HOLE IN THIS AREA

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'	NAME: <b>Micro-SIM Card Connector</b>
X.X	±0.25	X.X'	±4'	
X.XX	±0.15	X.XX'	±3'	
X.XXX	±0.10	X.XXX'	±2'	
PROJ.				DRAWN Henry NoV.29.2021
UNIT mm		SCALE 1:1		
CUSTOMER DRAWING				CHECKED Henry Nov.29.2021
APPROVAL Simon Mar.13.2015				DWG NO.: MUP-C791-004
				SHEET 1/1
				REVISION X1

